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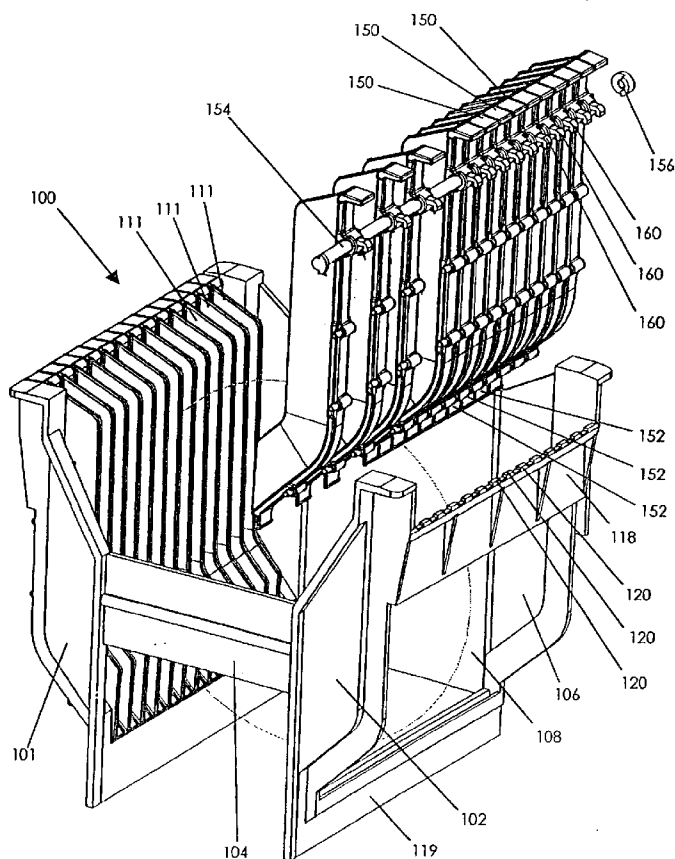
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(54) Title: THIN WAFER CARRIER



(57) Abstract: A wafer carrier (100) for carrying a plurality of axially aligned thin circular wafers. The wafer carrier has a framework portion (101) formed from a pair of end members (102, 106) connected by a plurality of side support members (118, 119). A pair of opposing sidewall (110) assemblies is positioned between the pair of end members, and is attached to at least one side support member. Each sidewall assembly has a plurality of shelves (111) defining a plurality of slots (112) for receiving a wafer (W). The sidewall assemblies are formed from a plurality of stacked together individual shelf members (150). Each shelf member has a body portion with an upper surface and a lower surface. The lower surface has a plurality of pegs (158) which are positioned to be received by a plurality of apertures (159) formed in the upper surface of an immediately adjacent individual shelf member (150).



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